WIREBONDS STATUS

dE				E-front				E-back				Last checked	
strip n.:	1st	2nd	3rd	strip n.:	1st	2nd	3rd	strip n.:	1st	2nd	3rd	date	detector
1				1	~		~	1				9/16/07	dE, Ef, Eb
2				2		~		2					
3				3				3					
4				4				4					
5				5				5					
6				6				6					
7				7				7					
8				8				8					
9				9				9		/?			
10				10				10			/?		
11				11				11		/?			
12				12				12	/?				
13				13				13	/?				
14				14				14	/?				
15				15				15					
16				16		~		16					
17				17				17					
18				18				18	/?				
19				19				19					
20				20				20					
21				21				21					
22				22				22					
23				23			~	23					
24				24				24					
25				25				25		/?			
26				26				26		/?			
27				27				27					
28				28				28		/?			
29				29				29			/?		
30				30	~	~		30					
31				31	~	~	~	31					
32				32				32					

Legend:

X = bond missing / = bond broken ~ = bond damaged

T2 O

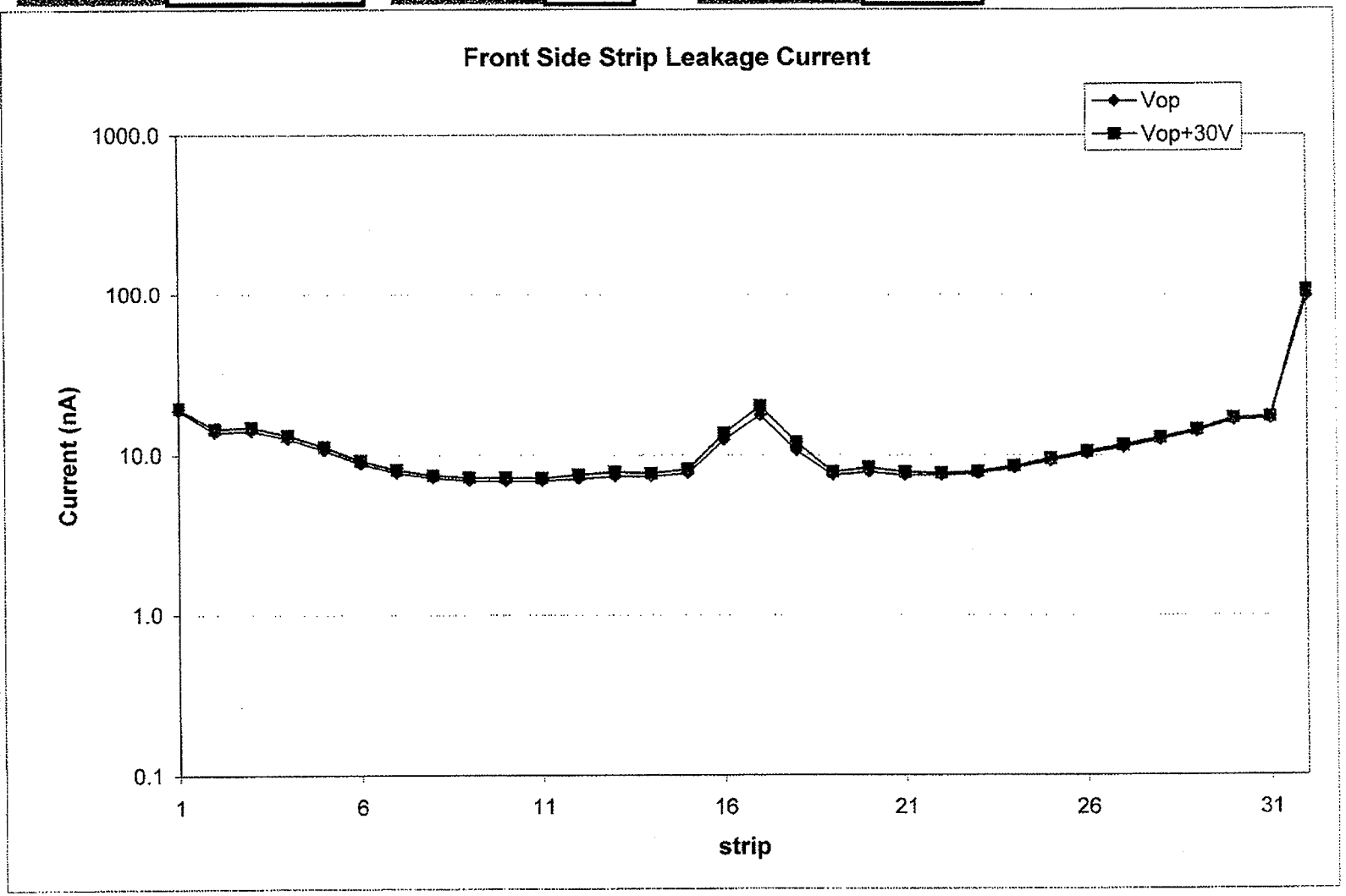
AE = 2260-9
E = 2085-8

Detector Profile BB7-1500

Front Side Data

Wafer No.: 2085-8 **Thickness:** 1496 um **Voltage Op.** 230 Volts

Strip	Current (nA) Vop	Vop+30V
1	18.79	19.34
2	13.764	14.463
3	14.067	14.79
4	12.562	13.21
5	10.686	11.23
6	8.853	9.245
7	7.744	8.088
8	7.185	7.479
9	6.934	7.232
10	6.876	7.258
11	6.895	7.196
12	7.081	7.552
13	7.359	7.858
14	7.379	7.727
15	7.716	8.185
16	12.373	13.545
17	17.542	19.91
18	10.651	11.953
19	7.519	7.887
20	7.834	8.384
21	7.498	7.864
22	7.486	7.748
23	7.694	7.949
24	8.332	8.606
25	9.251	9.546
26	10.206	10.529
27	11.145	11.493
28	12.408	12.791
29	13.883	14.319
30	16.324	16.92
31	16.645	17.209
32	97.42	108.06
total	416.1	445.566



Micron Semiconductor
05/06/03

INDIANA UNIVERSITY
BACK RESISTANCE MEASUREMENT:

DATE: 04/06/03
DEVICE TYPE: HIRA BB7-D/S-1500
DEVICE NUMBER: 2085-8
THICKNESS: 1496uM
OPERATING VOLTAGE: 230V

CHANNEL	OV	V.OP	V.OP + 30V
1-2	2.8KΩ	426KΩ	>1MΩ
2-3	2.9KΩ	316KΩ	>1MΩ
3-4	2.9KΩ	318KΩ	>1MΩ
4-5	3.0KΩ	337KΩ	>1MΩ
5-6	2.9KΩ	496KΩ	>1MΩ
6-7	3.0KΩ	564KΩ	>1MΩ
7-8	3.0KΩ	169KΩ	280KΩ
8-9	3.0KΩ	893KΩ	>1MΩ
9-10	3.1KΩ	163KΩ	357KΩ
10-11	3.0KΩ	122KΩ	>1MΩ
11-12	2.9KΩ	402KΩ	>1MΩ
12-13	2.8KΩ	101KΩ	>1MΩ
13-14	2.8KΩ	730KΩ	728KΩ
14-15	2.8KΩ	183KΩ	>1MΩ
15-16	3.0KΩ	1MΩ	>1MΩ
16-17	3.0KΩ	183KΩ	>1MΩ
17-18	3.0KΩ	757KΩ	>1MΩ
18-19	2.9KΩ	1MΩ	>1MΩ
19-20	2.9KΩ	433KΩ	>1MΩ
20-21	2.9KΩ	751KΩ	>1MΩ
21-22	2.9KΩ	887KΩ	>1MΩ
22-23	2.8KΩ	146KΩ	>1MΩ
23-24	2.9KΩ	>1MΩ	>1MΩ
24-25	3.0KΩ	>1MΩ	>1MΩ
25-26	2.9KΩ	>1MΩ	>1MΩ
26-27	3.0KΩ	>1MΩ	>1MΩ
27-28	2.9KΩ	>1MΩ	>1MΩ
28-29	2.9KΩ	>1MΩ	>1MΩ
29-30	2.9KΩ	>1MΩ	>1MΩ
30-31	2.8KΩ	>1MΩ	>1MΩ
31-32	2.7KΩ	162KΩ	702KΩ

MICRON SEMICONDUCTOR LTD.

Resolution Plot

HIRA BB7-1500

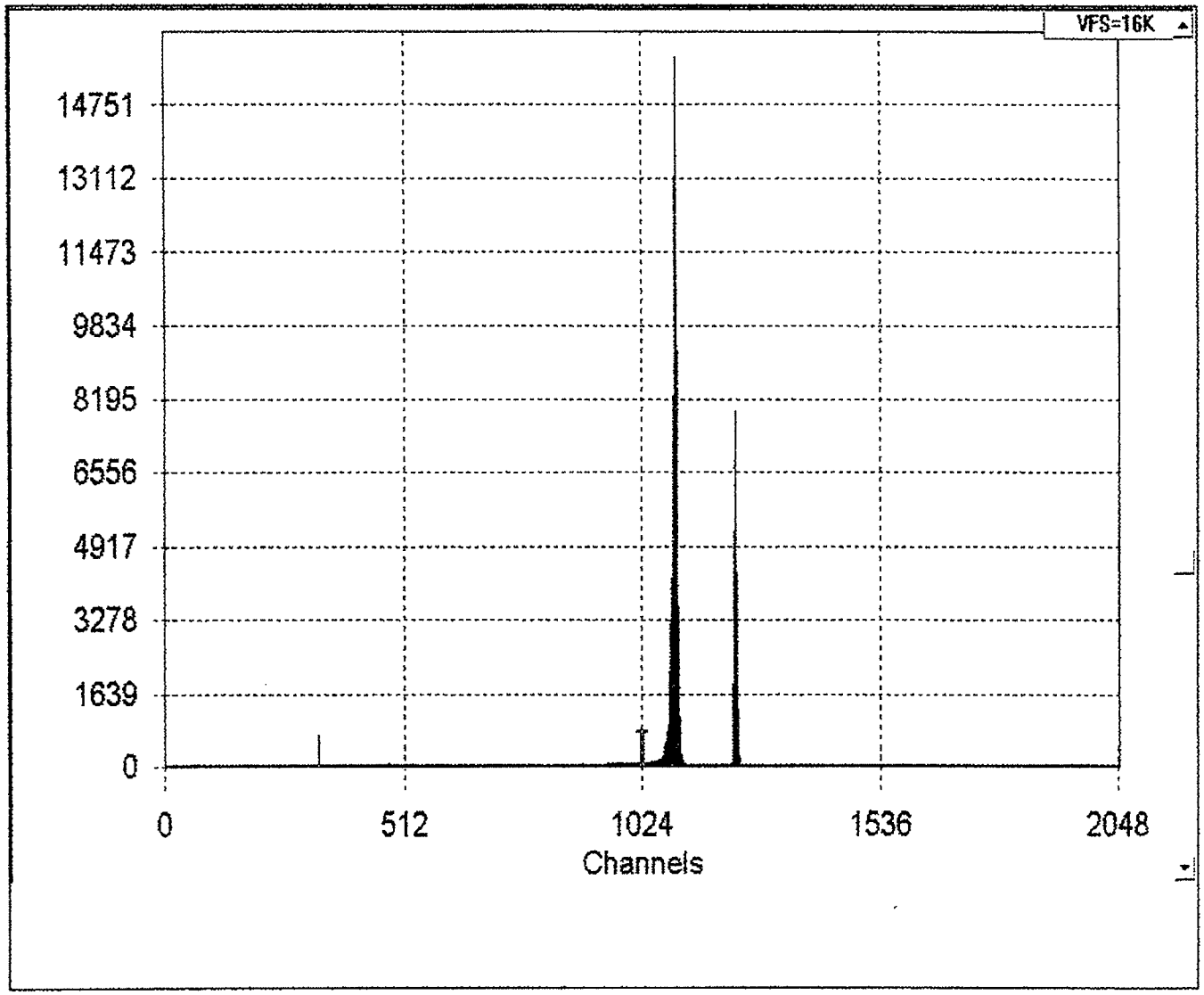
Wafer No.: 2085-8 **Thickness:** 1496 um

JUNCTION

DET LINE:	34.3	KeV
SYSTEM:	22.6	KeV
CAL:	25.8	KeV

OHMIC

DET LINE:	35	KeV
SYSTEM:	22.4	KeV
CALC:	26.8	KeV



Source Am 241

Rise Time 1

Flat Top 0

BIAS VOLTS= 250 V **Leakage** 500 nA

Micron Semiconductor
06/06/2003

Si-detector Inspection Record

Date: 9/16/07 **Time:** 5:40PM

Tel n.: 0 **Inspected detector(s):** dE, E (f+b)

1st inspector: Vlad HENZL

2nd inspector: JENNY LEE

WIREBONDS STATUS

dE				E-front				E-back			
strip n.:	1st	2nd	3rd	strip n.:	1st	2nd	3rd	strip n.:	1st	2nd	3rd
1				1	~		~	1			
2				2		~		2			
3				3				3			
4				4				4			
5				5				5			
6				6				6			
7				7				7			
8				8				8			
9				9				9		/	
10				10				10			/
11				11				11		/	
12				12				12	/		
13				13				13	/		
14				14				14	/?		
15				15				15			
16				16		~		16			
17				17				17			
18				18				18	/		
19				19				19			
20				20				20			
21				21				21			
22				22				22			
23				23			~	23			
24				24				24			
25				25				25		/	
26				26				26		/	
27				27				27			
28				28				28		/	
29				29				29			/
30				30	~	~		30			
31				31	~	~	~	31			
32				32				32			

Legend:

X = bond missing / = bond broken ~ = bond damaged

Overall detector status:

(e.g. dusty surface, scratches, dirty frame and/or cable, status of telescope can ...)

inspection after turbo fredd down + vacuum invasion

dE looks OK

detector is dusty !!

E.B. - difficult to see, possibly unbonded.

Noise tests of detector n.: 2085-8 in telescope n.: 0

	Date		8-29-07	10-10-07	10-31-07							
	electronics		CLASIC	CHIP	CHIP							
E back	**Chip 0 or shaper 0**	chn 0	2.3 mV	100 mV	~85/120							
		1	2.3	28	~37							
		2	2.3	28	37							
		3	2.3	28	37							
		4	2.3	28	37							
		5	2.3	28	37							
		6	2.3	28	37							
		7	2.3	28	37							
		8	2.3	28	37							
		9	2.3	28	37							
		10	2.3	28	37							
		11	2.3	28	37							
		12	2.3	28	37							
		13	2.3	28	37							
		14	2.3	28	37							
		15	~16.0	28	37							
	Chip 1 or shaper 1	chn 0	~15.0	31	37							
		1	~2.5 *	30	37							
		2	2.0	30	37							
		3	2.0	29	37							
		4	2.0	29	37							
		5	2.0	32	37							
		6	2.0	29	37							
		7	2.0	29	37							
		8	2.0	29	37							
		9	2.0	29	37							
		10	2.5 *	29	37							
		11	3.5	29	37							
		12	3.5	28	37							
		13	3.5	28	37							
		14	3.5	29	37							
		15	~5.3	100 mV	~105							
E front	**Chip 0 or shaper 2**	chn 0	3.8	360 mV	~310							
		1	2.2	~30	37							
		2	3.7	30	37							
		3	3.2	30	37							
		4	3.2	30	37							
		5	3.2	30	37							
		6	3.2	30	37							
		7	3.5	30	37							
		8	3.2	30	37							
		9	3.2	30	37							
		10	3.2	30	37							
		11	3.2	30	37							
		12	3.2	30	37							
		13	3.2	30	37							
		14	3.2	30	37							
		15	~50.0	30	37							
	Chip 1 or shaper 3	chn 0	~10.0	30	37							
		1	3.2	30	37							
		2	3.2	30	37							
		3	3.2	30	37							
		4	4.7	30	37							
		5	4.7	30	37							
		6	4.7	30	37							
		7	4.7	30	37							
		8	3.3	30	37							
		9	3.3	30	37							
		10	3.3	30	37							
		11	3.3	30	37							
		12	3.3	30	37							
		13	3.3	30	37							
		14	3.3	30	37							
		15	3.5	~80 mV	~80 mV							

* unstable thanks before 05.33 exp

+ after first part of exp

Si-detector Inspection Record

Date: 10/5/2007 **Time:** 10:00pm **Tel n.:** 0

Inspected detector(s): dE(2266-9)+E=(2085-8)

What occasion : dE part back in can

1st inspector: Vlad HENZL

2nd inspector: Daniela HENZLOVA

WIREBONDS STATUS

dE					E-front					E-back			
strip n.:	1st	2nd	3rd		strip n.:	1st	2nd	3rd		strip n.:	1st	2nd	3rd
1					1	~	~	~		1			
2					2	~	~			2			
3					3					3			
4					4					4			
5					5					5			
6					6					6			
7					7					7			
8					8					8			
9					9					9			
10					10					10			
11					11					11			
12					12					12			
13					13					13			
14					14					14			
15					15					15			
16					16		~			16			
17					17					17			
18					18					18			
19					19					19			
20					20			~		20			
21					21					21			
22					22					22			
23					23			~		23			
24					24					24			
25					25					25			
26					26					26			
27					27					27			
28					28					28			
29					29					29			
30					30	~	~	~		30			
31					31	~	~	~		31			
32					32					32			

Legend:

X = bond missing / = bond broken ~ = bond damaged

Overall detector status:

(e.g. dusty surface, scratches, dirty frame and/or cable, status of telescope can ...)